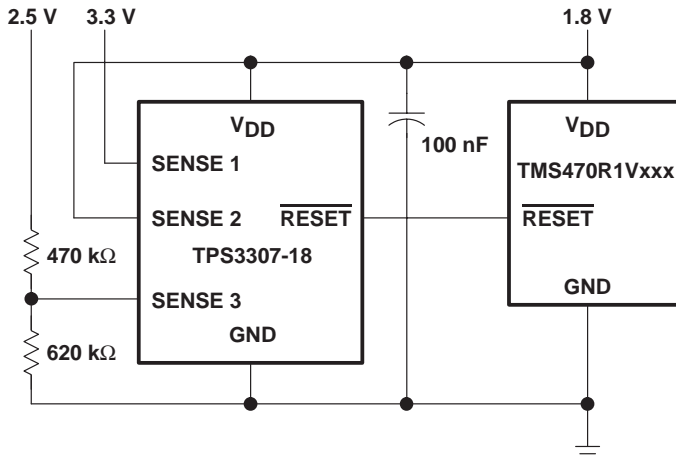
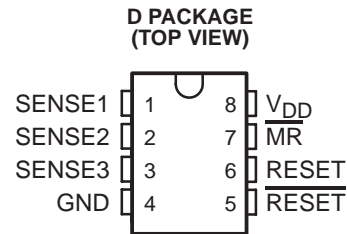


- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Triple Supervisory Circuits for DSP and Processor-Based Systems
- Power-On Reset Generator with Fixed Delay Time of 200 ms, No External Capacitor Needed
- Temperature-Compensated Voltage Reference
- Maximum Supply Current of 40 μ A
- Supply Voltage Range . . . 2 V to 6 V
- Defined $\overline{\text{RESET}}$ Output from $V_{\text{DD}} \geq 1.1$ V
- SO-8 Package
- Temperature Range . . . -40°C to 125°C

typical applications

Figure 1 lists some of the typical applications for the TPS3307 family, and a schematic diagram for a processor-based system application. This application uses TI part numbers TPS3307-18 and TMS470R1Vxxx.



- Automotive applications using DSPs, Microcontrollers or Microprocessors
- Industrial Equipment
- Programmable Controls
- Automotive Systems

Figure 1. Applications Using the TPS3307-18

description

The TPS3307-18 is a micropower supply voltage supervisor designed for circuit initialization primarily in automotive DSP and processor-based systems, which require more than one supply voltage.

The TPS3307-18 is designed for monitoring three independent supply voltages: 3.3 V/1.8 V/adj.. The adjustable SENSE input allows the monitoring of any supply voltage >1.25 V.

The various supply voltage supervisors are designed to monitor the nominal supply voltage as shown in the following supply voltage monitoring table.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TPS3307-18-Q1

TRIPLE PROCESSOR SUPERVISORS

SGLS136A – NOVEMBER 2002 – REVISED APRIL 2008

description (continued)

SUPPLY VOLTAGE MONITORING

DEVICE	NOMINAL SUPERVISED VOLTAGE			THRESHOLD VOLTAGE (TYP)		
	SENSE1	SENSE2	SENSE3	SENSE1	SENSE2	SENSE3
TPS3307-18	3.3 V	1.8 V	User defined	2.93 V	1.68 V	1.25 V†

† The actual sense voltage has to be adjusted by an external resistor divider according to the application requirements.

During power-on, $\overline{\text{RESET}}$ is asserted when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supply voltage supervisor monitors the SENSEn inputs and keeps $\overline{\text{RESET}}$ active as long as SENSEn remain below the threshold voltage V_{IT+} .

An internal timer delays the return of the $\overline{\text{RESET}}$ output to the inactive state (high) to ensure proper system reset. The delay time, $t_{d,typ} = 200$ ms, starts after all SENSEn inputs have risen above the threshold voltage V_{IT+} . When the voltage at any SENSE input drops below the threshold voltage V_{IT-} , the $\overline{\text{RESET}}$ output becomes active (low) again.

The TPS3307-18 incorporates a manual reset input, $\overline{\text{MR}}$. A low level at $\overline{\text{MR}}$ causes $\overline{\text{RESET}}$ to become active. In addition to the active-low $\overline{\text{RESET}}$ output, the TPS3307-18 includes an active-high RESET output.

The device is available in a standard 8-pin SO package, and is characterized for operation over a temperature range of -40°C to 125°C .

ORDERING INFORMATION†

TA	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	Small Outline (D)	Tape and Reel	TPS3307-18QDRQ1	30718Q

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.

FUNCTION/TRUTH TABLES

$\overline{\text{MR}}$	SENSE1 > V_{IT1}	SENSE2 > V_{IT2}	SENSE3 > V_{IT3}	$\overline{\text{RESET}}$	RESET
L	X	X	X	L	H
H	0	0	0	L	H
H	0	0	1	L	H
H	0	1	0	L	H
H	0	1	1	L	H
H	1	0	0	L	H
H	1	0	1	L	H
H	1	1	0	L	H
H	1	1	1	H	L

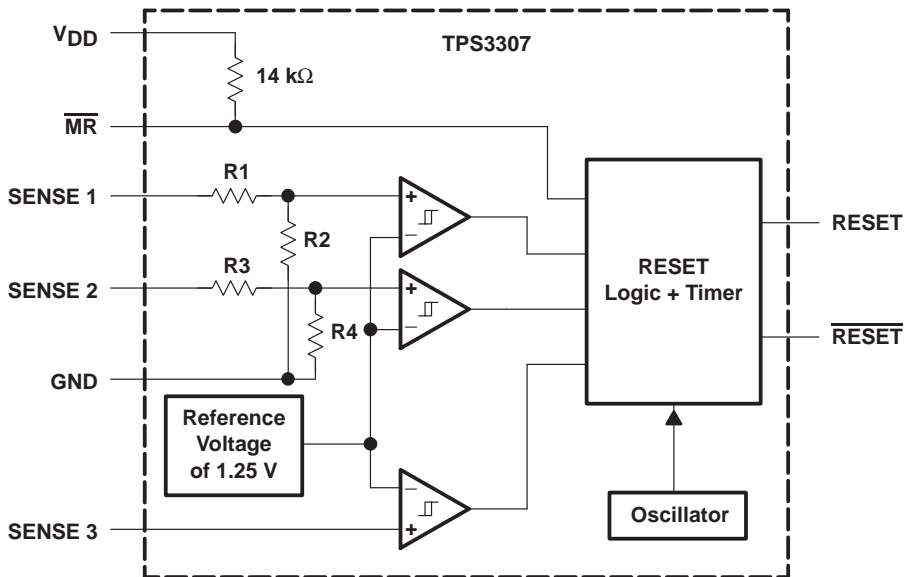
X = Don't care

PowerPAD is a trademark of Texas Instruments Incorporated.

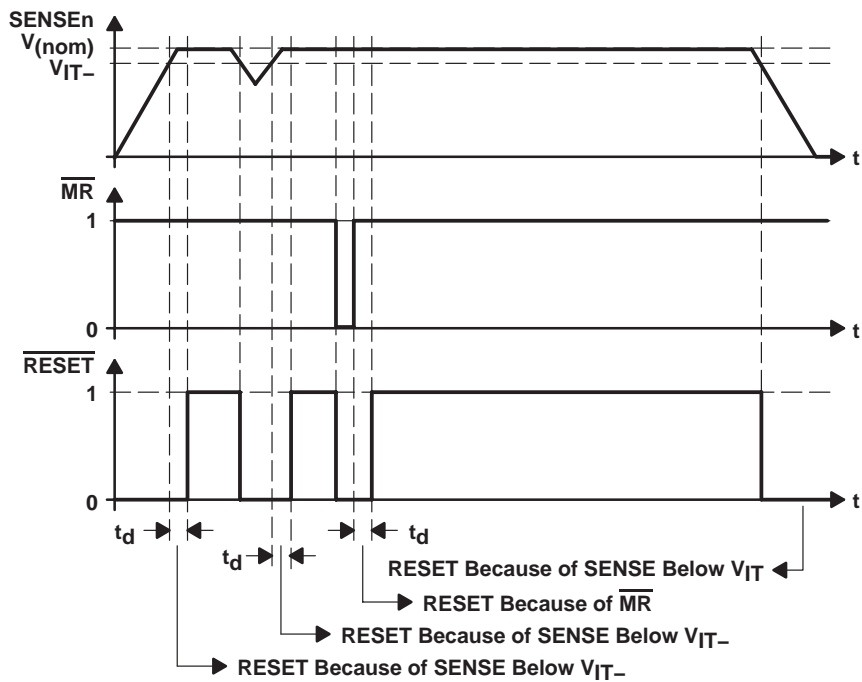


POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

functional block diagram



timing diagram



TPS3307-18-Q1

TRIPLE PROCESSOR SUPERVISORS

SGLS136A – NOVEMBER 2002 – REVISED APRIL 2008

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{DD} (see Note1)	7 V
All other pins (see Note 1)	-0.3 V to 7 V
Maximum low output current, I_{OL}	5 mA
Maximum high output current, I_{OH}	-5 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	± 20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	± 20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A	-40°C to 125°C
Storage temperature range, T_{stg}	-65°C to 150°C
Soldering temperature	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND. For reliable operation the device must not be operated at 7 V for more than $t = 1000$ h continuously.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW

recommended operating conditions at specified temperature range

	MIN	MAX	UNIT
Supply voltage, V_{DD}	2	6	V
Input voltage at \overline{MR} and SENSE3, V_I	0	$V_{DD}+0.3$	V
Input voltage at SENSE1 and SENSE2, V_I	0	$(V_{DD}+0.3)V_{IT}/1.25V$	V
High-level input voltage at \overline{MR} , V_{IH}	$0.7 \times V_{DD}$		V
Low-level input voltage at \overline{MR} , V_{IL}	$0.3 \times V_{DD}$		V
Input transition rise and fall rate at \overline{MR} , $\Delta t/\Delta V$	50		ns/V
Operating free-air temperature range, T_A	-40	125	°C



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
V _{OH}	High-level output voltage	V _{DD} = 2 V to 6 V, I _{OH} = -20 μA	V _{DD} - 0.2V			V	
		V _{DD} = 3.3 V, I _{OH} = -2 mA	V _{DD} - 0.4V				
		V _{DD} = 6 V, I _{OH} = -3 mA	V _{DD} - 0.4V				
V _{OL}	Low-level output voltage	V _{DD} = 2 V to 6 V, I _{OL} = 20 μA	0.2			V	
		V _{DD} = 3.3 V, I _{OL} = 2 mA	0.4				
		V _{DD} = 6 V, I _{OL} = 3 mA	0.4				
Power-up reset voltage (see Note 2)		V _{DD} ≥ 1.1 V, I _{OL} = 20 μA	0.4			V	
V _{IT-}	Negative-going input threshold voltage (see Note 3)	V _{DD} = 2 V to 6 V, T _A = -40°C to 125°C	VSENSE3	1.2	1.25	1.29	V
			VSENSE2	1.6	1.68	1.73	V
			VSENSE1	2.8	2.93	3.02	
V _{hys}	Hysteresis at VSENSEn input	V _{IT-} = 1.25 V	2	10	30	mV	
		V _{IT-} = 1.68 V	2	15	40		
		V _{IT-} = 2.93 V	3	30	60		
I _H	High-level input current	$\overline{\text{MR}}$	MR = 0.7 × V _{DD} , V _{DD} = 6 V		-130	-180	μA
		SENSE1	VSENSE1 = V _{DD} = 6 V		5	8	
		SENSE2	VSENSE2 = V _{DD} = 6 V		6	9	
		SENSE3	VSENSE3 = V _{DD}		-1	1	
I _L	Low-level input current	$\overline{\text{MR}}$	MR = 0 V, V _{DD} = 6 V		-430	-600	μA
		SENSEn	VSENSE1,2,3 = 0 V		-1	1	
I _{DD}	Supply current				40	μA	
C _i	Input capacitance	V _I = 0 V to V _{DD}		10		pF	

NOTES: 2. The lowest supply voltage at which RESET becomes active. t_r, V_{DD} ≥ 15 μs/V
 3. To ensure best stability of the threshold voltage, a bypass capacitor (ceramic 0.1 μF) should be placed close to the supply terminals.

TPS3307-18-Q1

TRIPLE PROCESSOR SUPERVISORS

SGLS136A – NOVEMBER 2002 – REVISED APRIL 2008

timing requirements at $V_{DD} = 2\text{ V to }6\text{ V}$, $R_L = 1\text{ M}\Omega$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_w	Pulse width	$V_{SENSEnL} = V_{IT-} - 0.2\text{ V}$, $V_{SENSEnH} = V_{IT+} + 0.2\text{ V}$	6	10		μs
		$V_{IH} = 0.7 \times V_{DD}$, $V_{IL} = 0.3 \times V_{DD}$	100	150		ns

switching characteristics at $V_{DD} = 2\text{ V to }6\text{ V}$, $R_L = 1\text{ M}\Omega$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_d	Delay time	$V_I(\text{SENSEn}) \geq V_{IT+} + 0.2\text{ V}$, $\overline{\text{MR}} \geq 0.7 \times V_{DD}$, See timing diagram	140	200	280	ms
t_{PHL}	Propagation (delay) time, high-to-low level output	$\overline{\text{MR}}$ to $\overline{\text{RESET}}$ $\overline{\text{MR}}$ to $\overline{\text{RESET}}$		200	600	ns
t_{PLH}	Propagation (delay) time, low-to-high level output	$\overline{\text{MR}}$ to $\overline{\text{RESET}}$ $\overline{\text{MR}}$ to $\overline{\text{RESET}}$				
t_{PHL}	Propagation (delay) time, high-to-low level output	SENSEn to $\overline{\text{RESET}}$		1	5	μs
t_{PLH}	Propagation (delay) time, low-to-high level output	SENSEn to $\overline{\text{RESET}}$				

TYPICAL CHARACTERISTICS

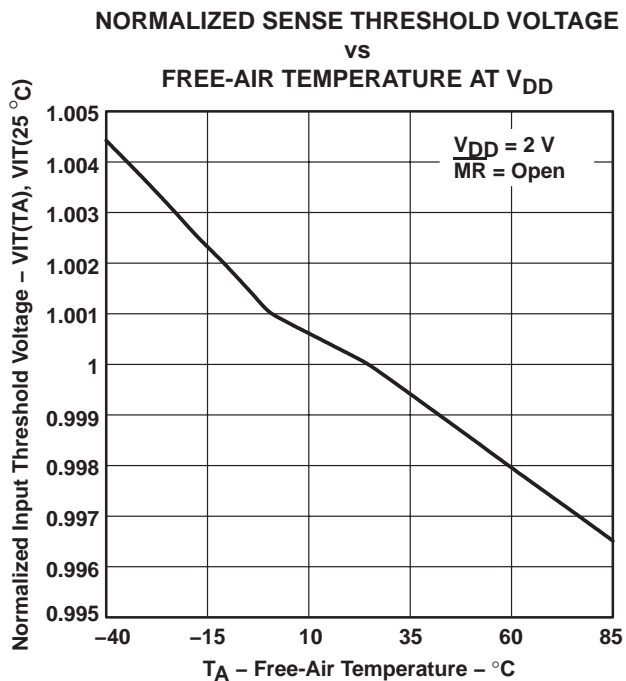


Figure 2

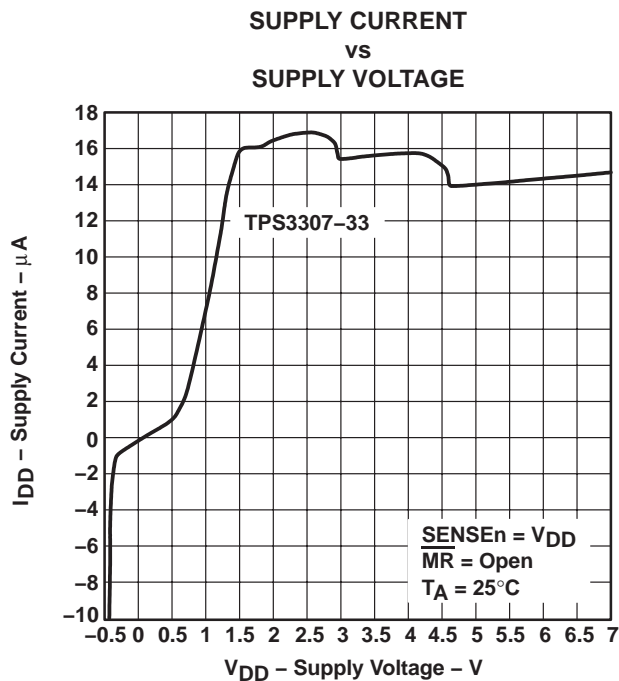


Figure 3

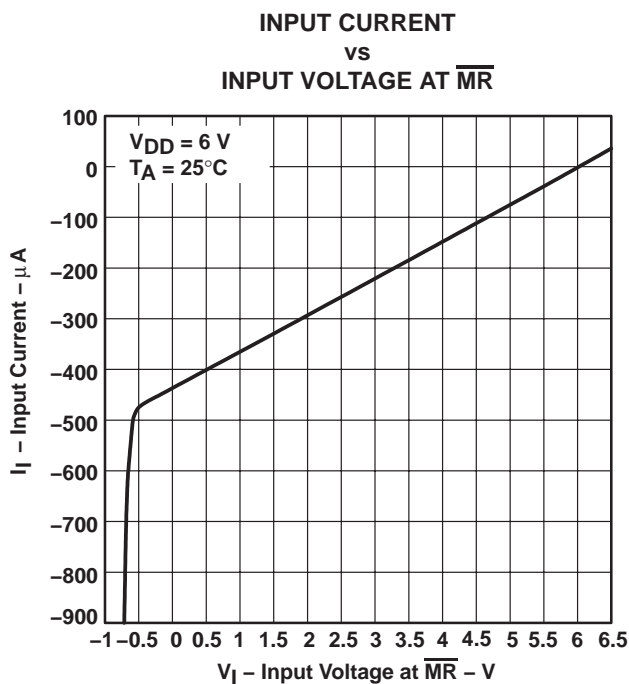


Figure 4

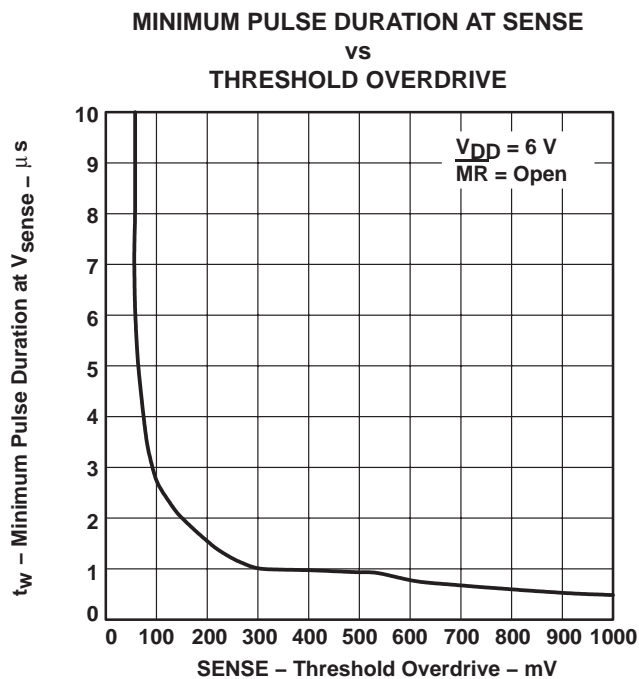


Figure 5

TPS3307-18-Q1

TRIPLE PROCESSOR SUPERVISORS

SGLS136A – NOVEMBER 2002 – REVISED APRIL 2008

TYPICAL CHARACTERISTICS

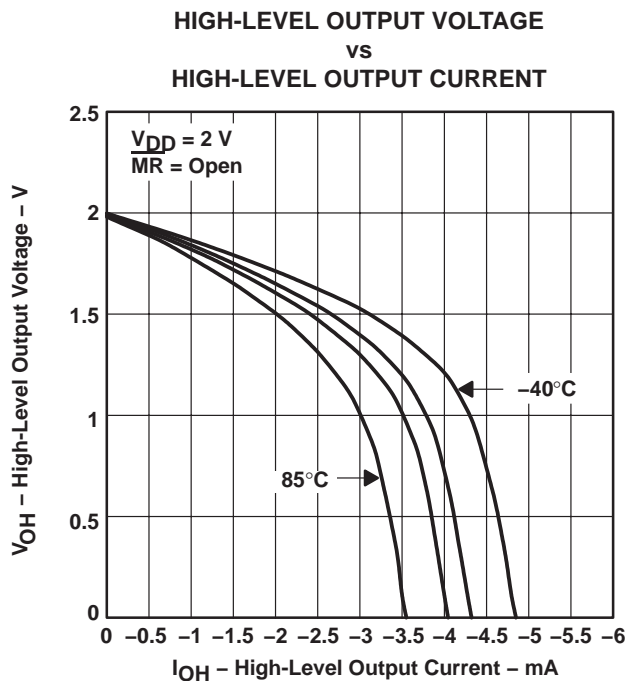


Figure 6

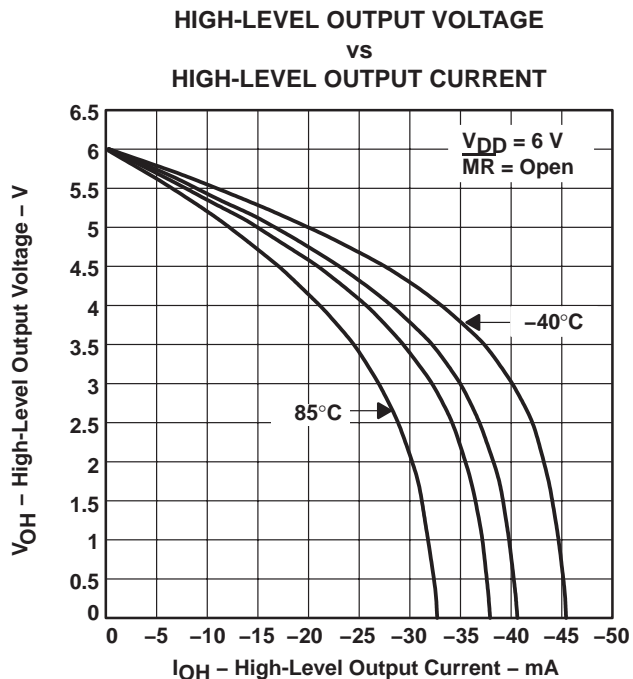


Figure 7

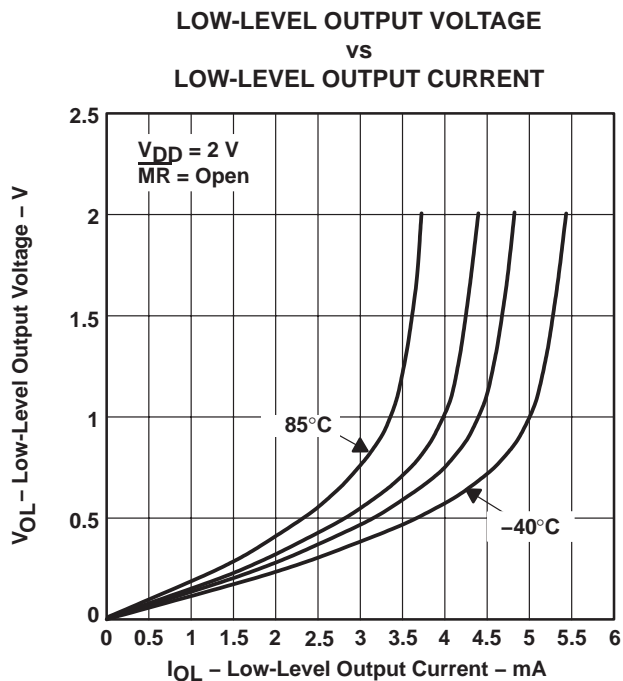


Figure 8

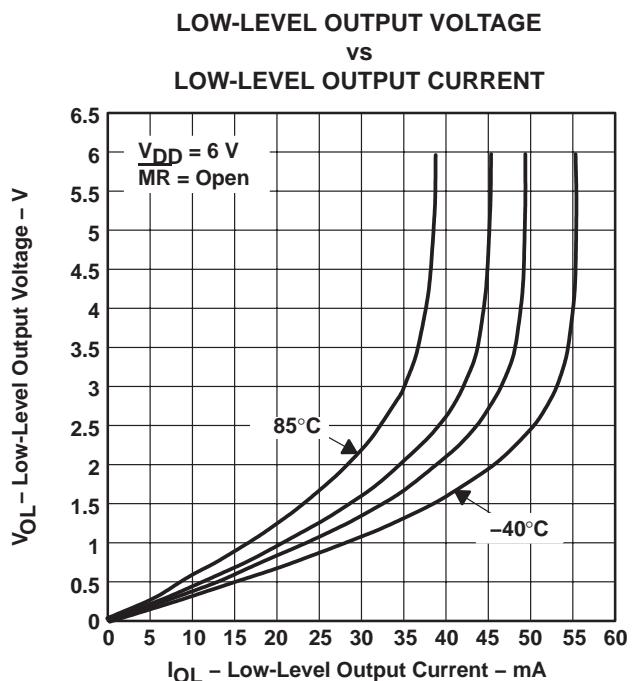


Figure 9

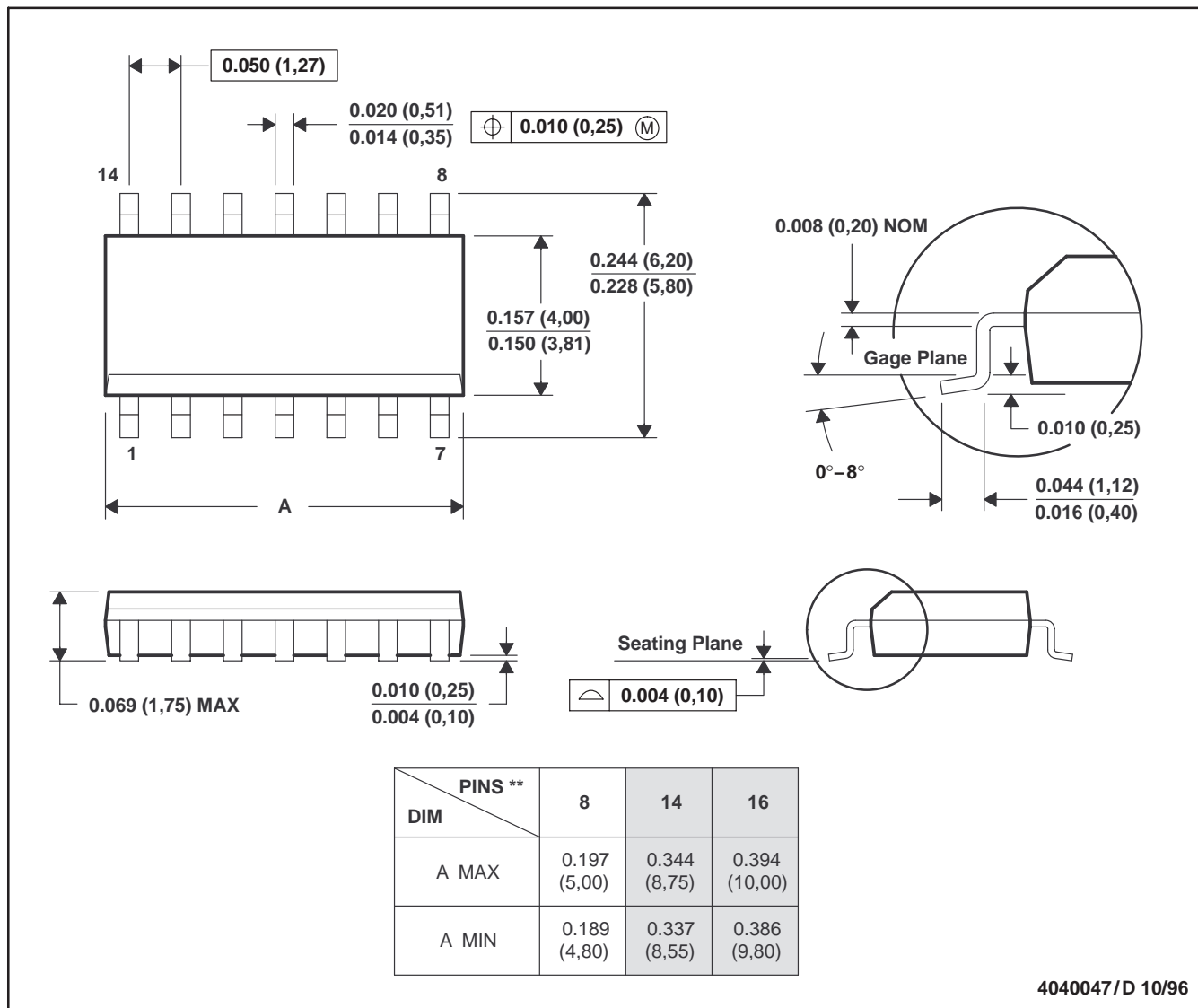


MECHANICAL DATA

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-012

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TPS3307-18QDRG4Q1	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3307-18QDRQ1	ACTIVE	SOIC	D	8	2500	TBD	CU NIPDAU	Level-1-220C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TPS3307-18-Q1 :

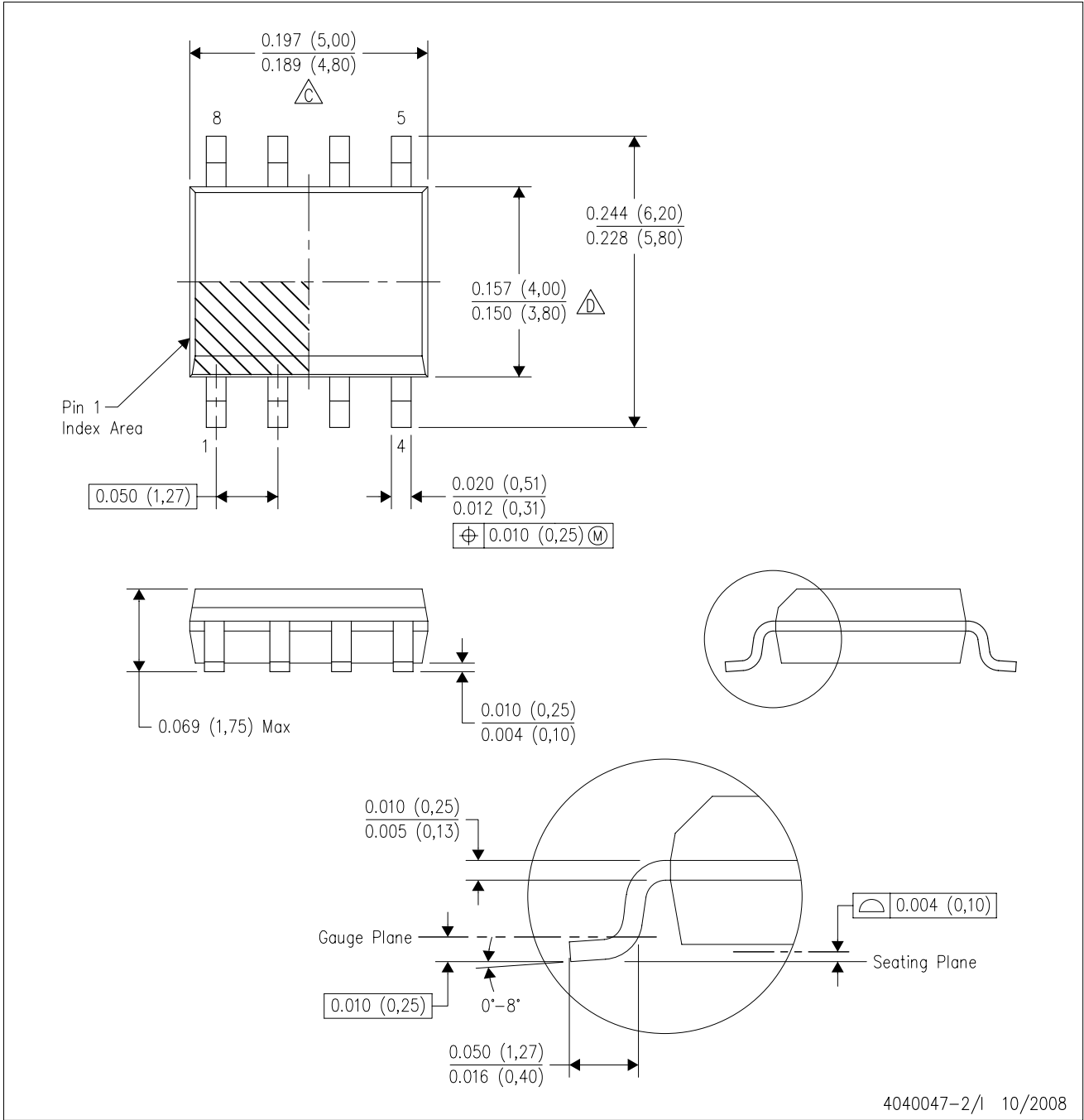
- Catalog: [TPS3307-18](#)
- Enhanced Product: [TPS3307-18-EP](#)
- Military: [TPS3307-18M](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-2/1 10/2008

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AA.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2008, Texas Instruments Incorporated